LINEAR SYSTEMS

Twenty-Five Years Of Quality Through Innovation

LSK489

LOW NOISE LOW CAPACITANCE MONOLITHIC DUAL N-CHANNEL JFET AMPLIFIER

FEATURES	
ULTRA LOW NOISE	e_n = 1.8nV/√Hz
LOW INPUT CAPACITANCE	Ciss = 4pF

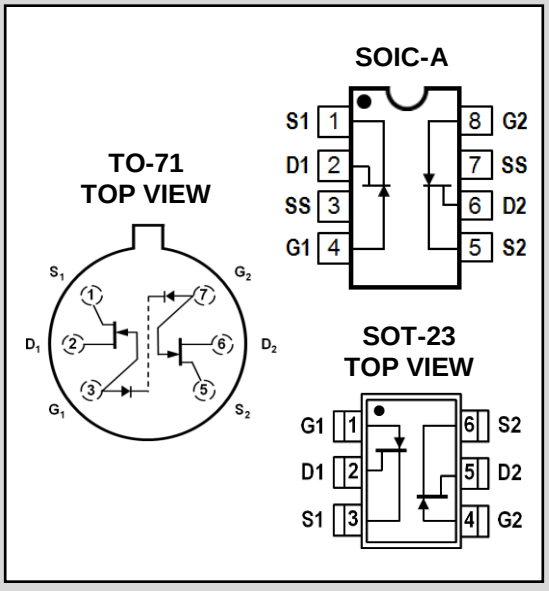
Features
- Reduced Noise due to process improvement
- Monolithic Design
- High slew rate
- Low offset/drift voltage
- Low gate leakage Igss & Ig
- High CMRR 102 dB

Benefits
- Tight differential voltage match vs. current
- Improved op amp speed settling time accuracy
- Minimum Input Error trimming error voltage
- Lower intermodulation distortion

Applications
- Wide band differential Amps
- High speed temperature compensated single ended input amplifier amps
- High speed comparators
- Impedance Converters

Description
The LSK 489 series of high performance monolithic dual JFETs features extremely low noise, tight offset voltage and low drift over temperature specifications, and is targeted for use in a wide range or precision instrumentation applications. This series has a wide selection of offset and drift specifications. The SST series SO-8 package provided ease of manufacturing and the symmetrical pinout prevents improper orientation. The SO-8 package is available with tape and reel options for compatibility with automatic assembly methods. (See packaging data)

ABSOLUTE MAXIMUM RATINGS[1] @ 25 °C (unless otherwise stated)	
Maximum Temperatures	
Storage Temperature	-55 to +150°C
Junction Operating Temperature	-55 to +150°C
Maximum Power Dissipation, TA = 25°C	
Continuous Power Dissipation, per side [4]	300mW
Power Dissipation, total [5]	500mW
Maximum Currents	
Gate Forward Current	$I_{G(F)}$ = 10mA
Maximum Voltages	
Gate to Source	V_{GSO} = 60V
Gate to Drain	V_{GDO} = 60V



* For equivalent single version, see LSK189

MATCHING CHARACTERISTICS @ 25°C (unless otherwise stated)

SYMBOL	CHARACTERISTIC	MIN	TYP	MAX	UNITS	CONDITIONS
$\lvert V_{GS1} - V_{GS2} \rvert$	Differential Gate to Source Cutoff Voltage			20	mV	V_{DS} = 10V, I_D = 1mA
$\frac{I_{DSS1}}{I_{DSS2}}$	Gate to Source Saturation Current Ratio	0.9		1.0		V_{DS} = 10V, V_{GS} = 0V
CMRR	**COMMON MODE REJECTION RATIO** $-20 \log \lvert \Delta V_{GS1-2}/\Delta V_{DS} \rvert$	95	102		dB	V_{DS} = 10V to 20V, I_D = 200µA

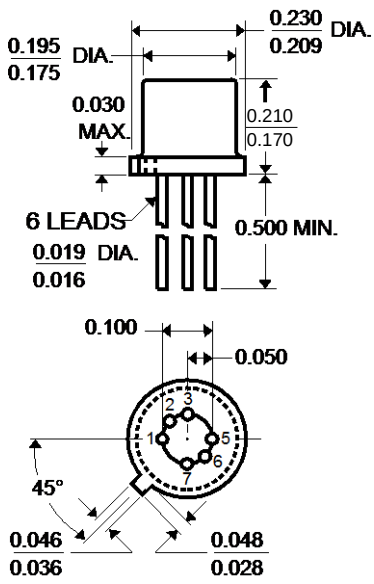
SYMBOL	CHARACTERISTIC	MIN	TYP	MAX	UNITS	CONDITIONS
e_n	Noise Voltage		1.8	2.0	nV/√Hz	V_{DS} = 15V, I_D = 2.0mA, *f* = 1kHz, NBW = 1Hz
e_n	Noise Voltage		2.8	3.5	nV/√Hz	V_{DS} = 15V, I_D = 2.0mA, *f* = 10Hz, NBW = 1Hz
C_{ISS}	Common Source Input Capacitance		4	8	pF	V_{DS} = 15V, I_D = 500µA, *f* = 1MHz
C_{RSS}	Common Source Reverse Transfer Capacitance			3	pF	

ELECTRICAL CHARACTERISTICS @ 25°C (unless otherwise stated)

SYMBOL	CHARACTERISTIC	MIN	TYP	MAX	UNITS	CONDITIONS
BV_{GSS}	Gate to Source Breakdown Voltage	-60			V	V_{DS} = 0, I_D = -1nA
$V_{(BR)G1 - G2}$	Gate to Gate Breakdown Voltage	±30	±45		V	I_G= ±1µA, I_D=I_S=0 A (Open Circuit)
$V_{GS(OFF)}$	Gate to Source Pinch-off Voltage	-1.5		-3.5	V	V_{DS} = 15V, I_D = 1nA
V_{GS}	Gate to Source Operating Voltage	-0.5		-3.5	V	V_{DS} = 15V, I_D = 500µA
I_{DSS}[2]	Drain to Source Saturation Current	2.5	5	15	mA	V_{DG} = 15V, V_{GS} = 0
I_G	Gate Operating Current		-2	-25	pA	V_{DG} = 15V, I_D = 200µA
			-0.8	-10	nA	T_A = 125°C
I_{GSS}	Gate to Source Leakage Current			-100	pA	V_{DG} = -15V, V_{DS} = 0
G_{fs}	Full Conductance Transconductance	1500			µS	V_{DG} = 15V, V_{GS} = 0, *f* = 1kHz
G_{fs}	Transconductance	1000	1500		µS	V_{DG} = 15V, I_D = 500µA
G_{OS}	Full Output Conductance			40	µS	V_{DG} = 15V, V_{GS} = 0
G_{OS}	Output Conductance		1.8	2.7	µS	V_{DG} = 15V, I_D = 200µA
NF	Noise Figure			0.5	dB	V_{DS} = 15V, V_{GS} = 0, R_G = 10MΩ, *f* = 100Hz, NBW = 6Hz

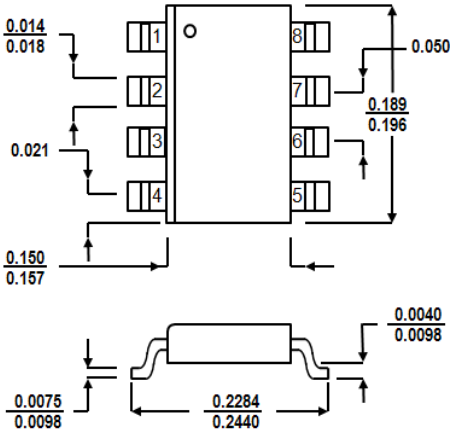
PACKAGE DIMENSIONS

TO-71
SIX LEAD



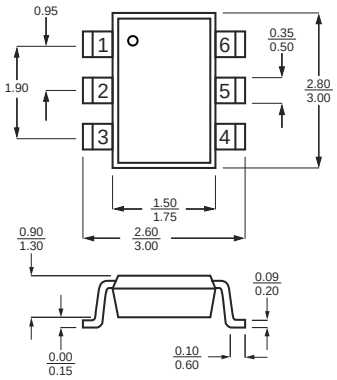
DIMENSIONS IN INCHES

SOIC-A



DIMENSIONS IN INCHES

SOT-23
SIX LEAD



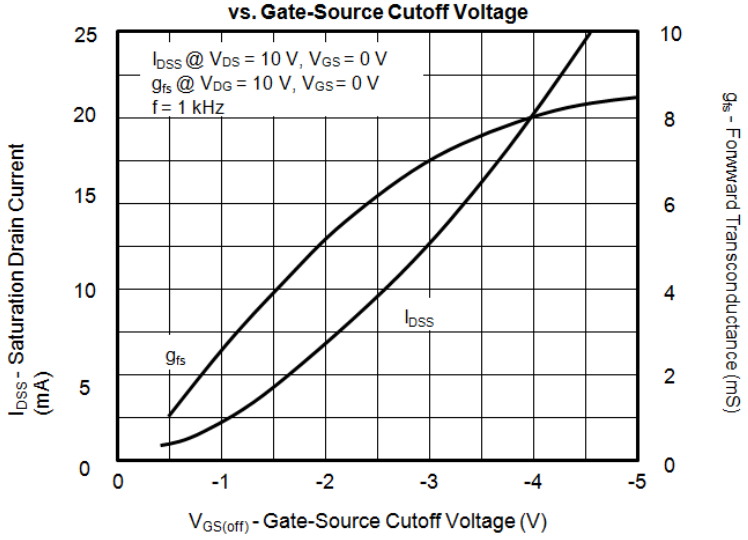
DIMENSIONS IN MILLIMETERS

NOTES

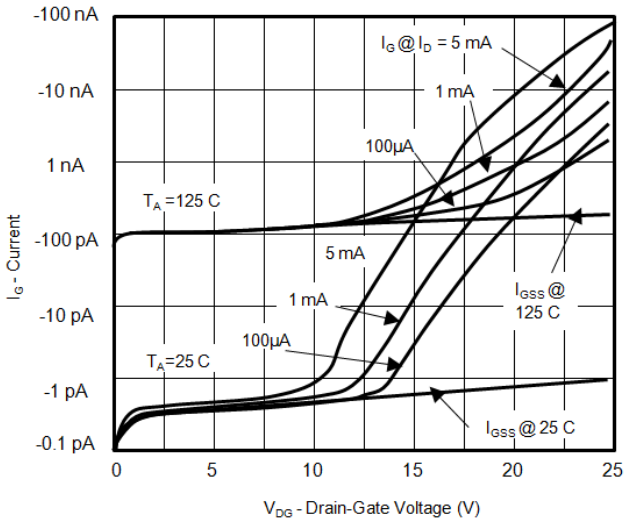
1. Absolute maximum ratings are limiting values above which serviceability may be impaired.
2. Pulse width ≤2$_{ms}$.
3. All MIN/TYP/MAX Limits are absolute values. Negative signs indicate electrical polarity only.
4. Derate 2.4 mW/°C above 25°C.
5. Derate 4 mW/°C above 25°C.

Typical Characteristics

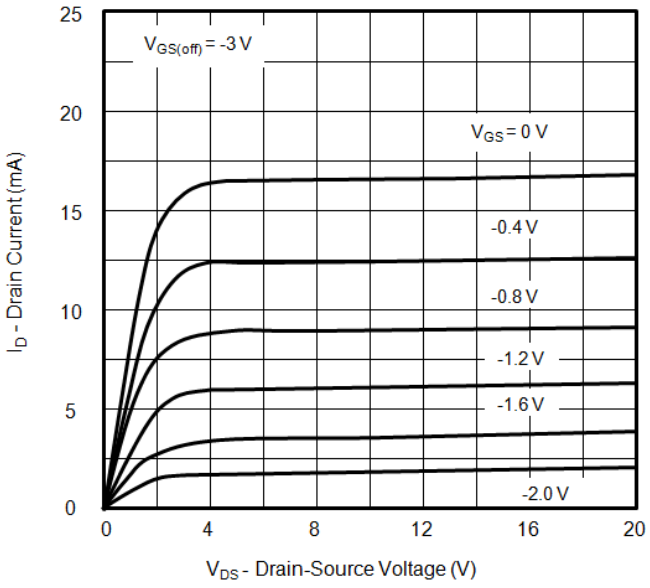
Drain Current and Transconductance vs. Gate-Source Cutoff Voltage



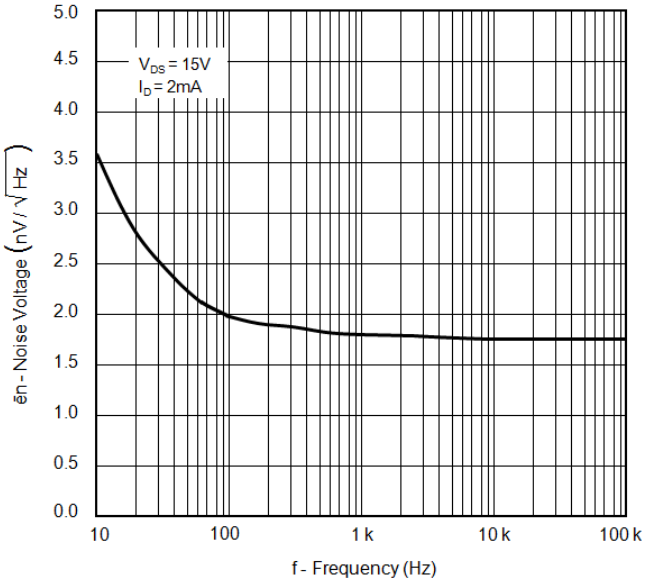
Operating Gate Current



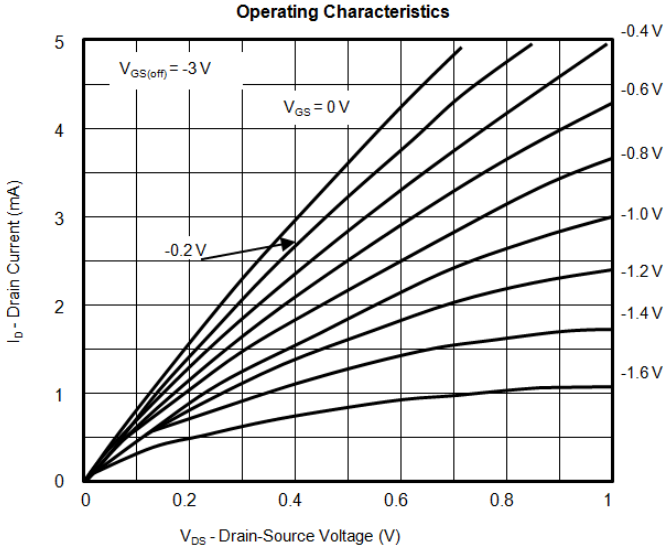
Output Characteristics



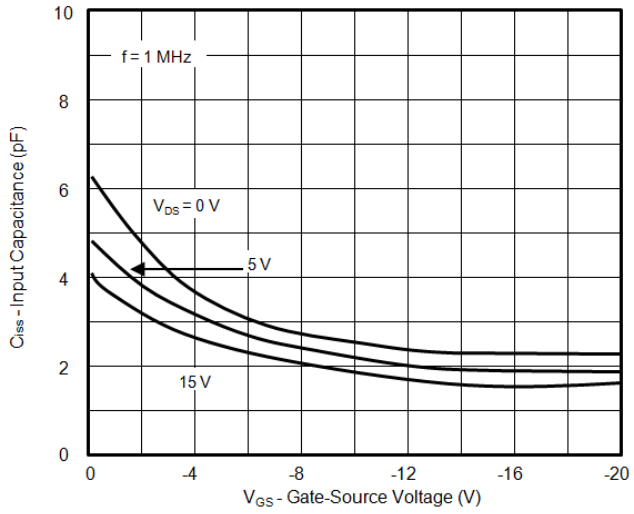
Equivalent Input Noise Voltage vs. Frequency



Operating Characteristics

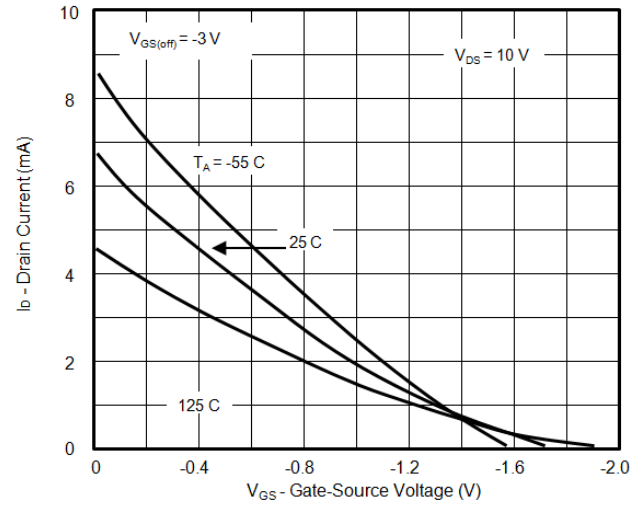


Common-Source Input Capacitance vs. Gate-Source Voltage

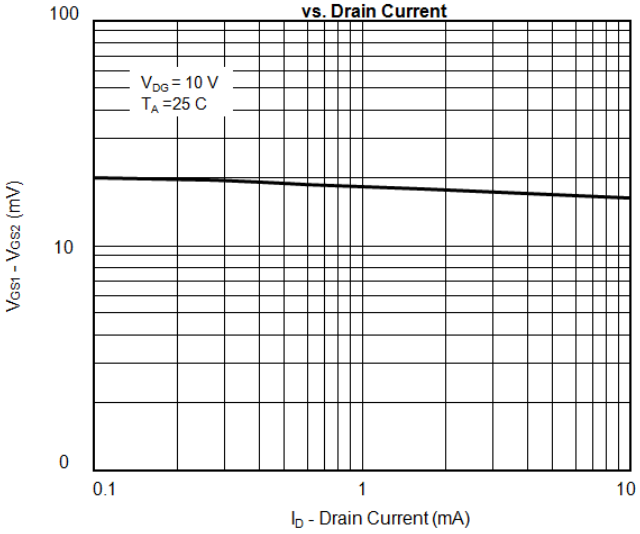


Typical Characteristics (Cont'd)

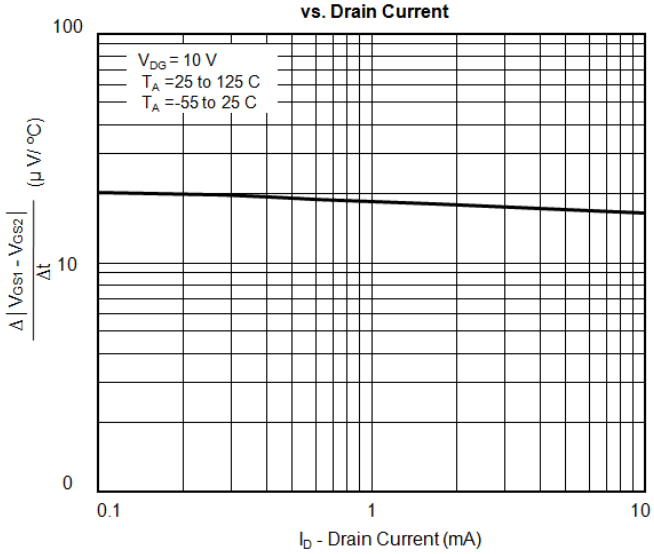
Transfer Characteristics



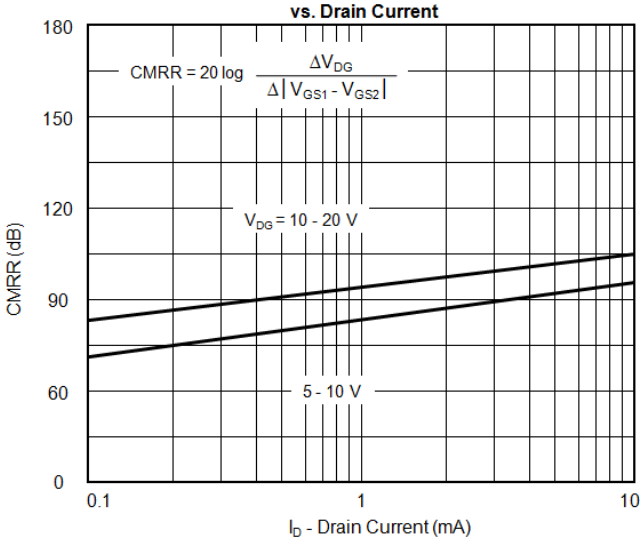
Gate-Source Differential Voltage vs. Drain Current



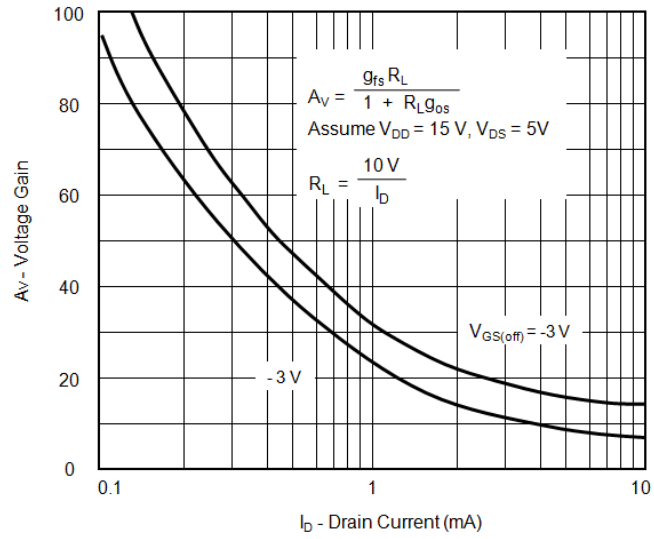
Voltage Differential with Temperature vs. Drain Current



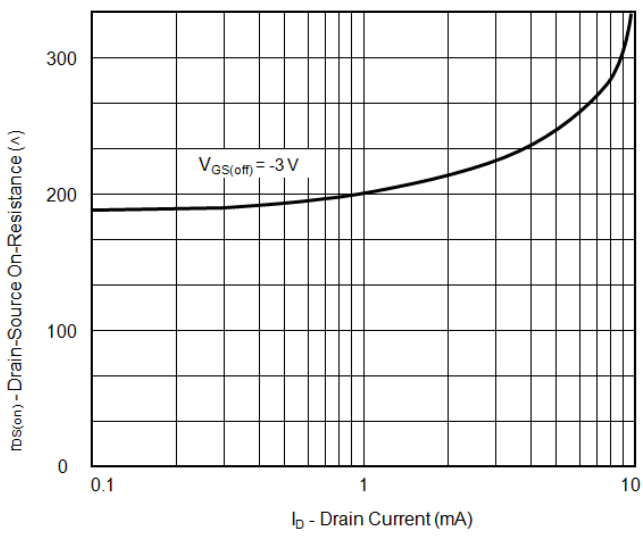
Common Mode Rejection Ration vs. Drain Current



Circuit Voltage Gain vs. Drain Current

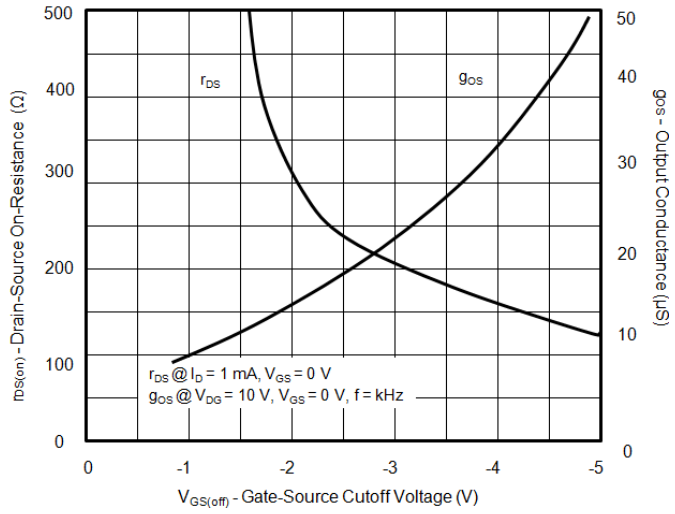


On-Resistance vs. Drain Current

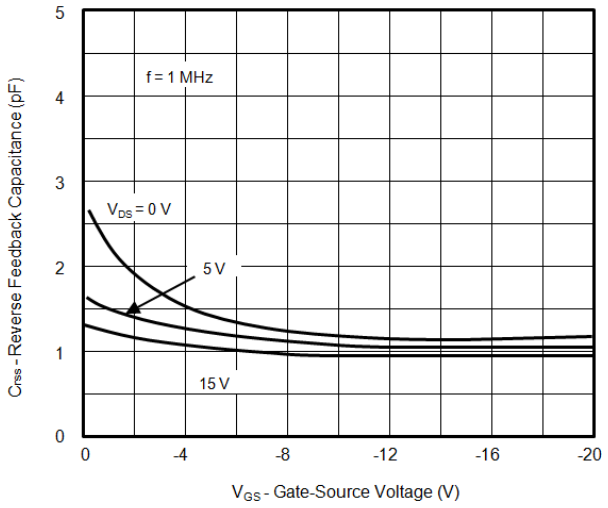


Typical Characteristics (Cont'd)

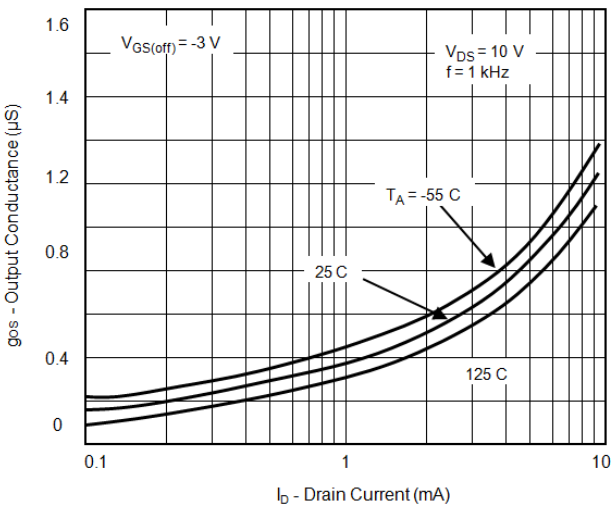
On-Resistance and Output Conductance vs. Gate-Source Cutoff Voltage



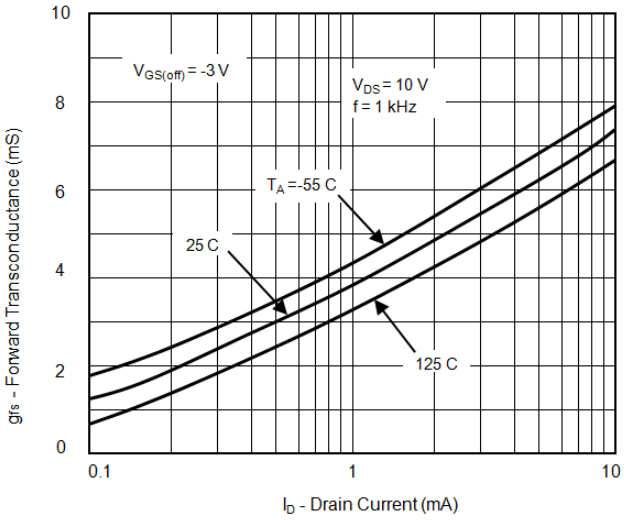
Common-Source Reverse Feedback Capacitance vs. Gate-Source Voltage



Output Conductance vs. Drain Current



Common-Source Forward Transconductance vs. Drain Current



Linear Integrated Systems (LIS) is a 25-year-old, third-generation precision semiconductor company providing high-quality discrete components. Expertise brought to LIS is based on processes and products developed at Amelco, Union Carbide, Intersil and Micro Power Systems by company President John H. Hall. Hall, a protégé of Silicon Valley legend Dr. Jean Hoerni, was the director of IC Development at Union Carbide, Co-Founder and Vice President of R&D at Intersil, and Founder/President of Micro Power Systems.